

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2571742

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHEN-HUA YU</td> <td>08/28/2013</td> </tr> <tr> <td>MIRNG-JI LII</td> <td>08/21/2013</td> </tr> <tr> <td>CHUNG-SHI LIU</td> <td>08/21/2013</td> </tr> <tr> <td>CHANG-CHIA HUANG</td> <td>08/23/2013</td> </tr> <tr> <td>CHIH-WEI LIN</td> <td>08/23/2013</td> </tr> <tr> <td>MING-DA CHENG</td> <td>08/21/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHEN-HUA YU	08/28/2013	MIRNG-JI LII	08/21/2013	CHUNG-SHI LIU	08/21/2013	CHANG-CHIA HUANG	08/23/2013	CHIH-WEI LIN	08/23/2013	MING-DA CHENG	08/21/2013
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RECEIVING PARTY DATA															
<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.	Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK	City:	HSINCHU	State/Country:	TAIWAN						
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PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14013503</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14013503										
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Application Number:	14013503														
CORRESPONDENCE DATA															
Fax Number:	(949)743-8963														
Phone:	949 387 2885														
Email:	ahong@wpatca.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	WPAT, PC INTELLECTUAL PROPERTY ATTORNEYS														
Address Line 1:	1100 QUAIL STREET, SUITE 202														
Address Line 4:	NEWPORT BEACH, CALIFORNIA 92660														
ATTORNEY DOCKET NUMBER:	18506-629														
NAME OF SUBMITTER:	ANTHONY KING														

Signature:	/Anthony King/
Date:	10/09/2013
Total Attachments: 2 source=US2741_Assg#page1.tif source=US2741_Assg#page2.tif	

**ASSIGNMENT**

WHEREAS, I(we), YU, CHEN-HUA, LIL MIRNG-JI, LIU, CHUNG-SHI, HUANG, CHANG-CHIA, LIN, CHIH-WEI and CHENG, MING-DA, whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled

**SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF**

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

☐ United States Design Patent was

☐ executed on:

☒ filed on: 2013/8/29 Serial No.: 14/013,503

☐ established by PCT International Patent Application No.: filed: designating the

United States of America

☐ issued on \_\_\_\_\_ as U.S. Patent No.: \_\_\_\_\_

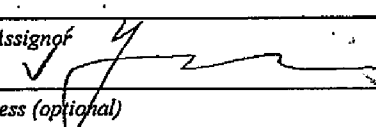
WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD. whose post office address is NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK, HSINCHU, TAIWAN, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

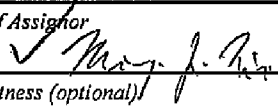
NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

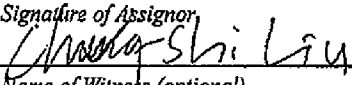
ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

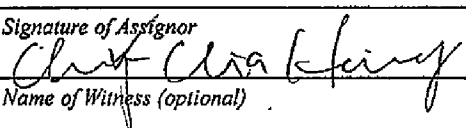
ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

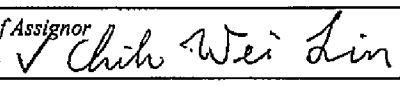
ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

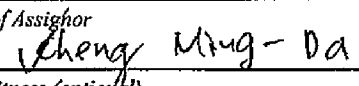
Assignor Name YU, CHEN-HUA	Address NO. 3, 38 WATERFRONT ROAD 2, HSINCHU CITY, TAIWAN (R.O.C.)
Signature of Assignor 	Date of Signature 8/28/13
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name LIU, MIRNG-JI	Address NO.9, LANE 9, DASIANG RD., SINPU TOWNSHIP, HSINCHU COUNTY 305, TAIWAN (R.O.C.)
Signature of Assignor 	Date of Signature 2013.8.21
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name LIU, CHUNG-SHI	Address 4F, NO. 178, GUANXIN EAST RD., HSINCHU CITY, TAIWAN (R.O.C.)
Signature of Assignor 	Date of Signature 2013.8.21
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name HUANG, CHANG-CHIA	Address 4F., NO.53-11, LN. 163, SEC. 1, GUANGFU RD., EAST DIST., HSINCHU CITY 300, TAIWAN (R.O.C.)
Signature of Assignor 	Date of Signature 2013.8.23
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name LIN, CHIH-WEI	Address 7F., NO.12, ALY. 7, LN. 42, ZILI ST., XINFENG TOWNSHIP, HSINCHU COUNTY 304, TAIWAN (R.O.C.)
Signature of Assignor 	Date of Signature 2013.8.23
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

Assignor Name CHENG, MING-DA	Address 8F, NO. 35, SHENGLI 6TH ST., SHIHSING VILLAGE, JHUBEI CITY, HSINCHU COUNTRY, TAIWAN (R.O.C.)
Signature of Assignor 	Date of Signature 2013.8.21
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)